

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT																			
NATURE OF CONVEYANCE:	ASSIGNMENT																			
CONVEYING PARTY DATA																				
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Shay Assaf</td><td>10/30/2008</td></tr> <tr><td>Venkatesh Babu</td><td>10/30/2008</td></tr> <tr><td>Robert D. Flores</td><td>10/30/2008</td></tr> <tr><td>Brendan Hickey</td><td>10/29/2008</td></tr> <tr><td>Krishna Kuttannair</td><td>10/30/2008</td></tr> <tr><td>Song J. Park</td><td>10/30/2008</td></tr> <tr><td>Adrian Rhee</td><td>10/30/2008</td></tr> <tr><td>Chongyang Chris Wang</td><td>10/30/2008</td></tr> </tbody> </table>			Name	Execution Date	Shay Assaf	10/30/2008	Venkatesh Babu	10/30/2008	Robert D. Flores	10/30/2008	Brendan Hickey	10/29/2008	Krishna Kuttannair	10/30/2008	Song J. Park	10/30/2008	Adrian Rhee	10/30/2008	Chongyang Chris Wang	10/30/2008
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="width: 20%;">Name:</td><td>Applied Materials, Inc.</td></tr> <tr><td>Street Address:</td><td>P.O. Box 450A</td></tr> <tr><td>City:</td><td>Santa Clara</td></tr> <tr><td>State/Country:</td><td>CALIFORNIA</td></tr> <tr><td>Postal Code:</td><td>95052</td></tr> </table>			Name:	Applied Materials, Inc.	Street Address:	P.O. Box 450A	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052								
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CORRESPONDENCE DATA																				
Fax Number: (408)986-3090 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 408-748-5524 Email: yolande_glass@contractor.amat.com Correspondent Name: Applied Materials Address Line 1: P.O. Box 450A Address Line 4: Santa Clara, CALIFORNIA 95052																				
ATTORNEY DOCKET NUMBER:	12906/ALRT/FEG CSS/CROCKE																			

PATENT

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REEL: 021853 FRAME: 0323

CH \$40.00 12244735

NAME OF SUBMITTER:

Yolande M. Glass

Total Attachments: 6

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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Shay Assaf 10164 Parkwood Drive #1 Cupertino, CA 95014	2)	Venkatesh Babu 2962 Abigail Lane San Jose, CA 95121
3)	Robert D. Flores 577 W. Rincon Ave Campbell, CA 95008	4)	Brendan Hickey
5)	Krishna Kuttannair 1790 Daltrey Way San Jose, CA 95008	6)	Song J. Park 1809 Pasco Del Cajon Pleasanton, CA 94566
	Adrian Rhee		Chongyang Chris Wang 3557 Rue Chene D'or San Jose, CA 95148

(hereinafter referred to as Assignors), have invented a certain invention entitled:

**METHOD AND SYSTEM FOR MANAGING PROCESS
JOBS IN A SEMICONDUCTOR FABRICATION FACILITY**

for which application for Letters Patent in the United States was filed on 10/02/08,

under Serial No. 12/244,735, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and

every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) 10/30/, 2008

Shay Assaf
Shay Assaf

2) _____, 2008

Venkatesh Babu

3) _____, 2008

Robert D. Flores

4) _____, 2008

Brendan Hickey

5) 10/30/, 2008

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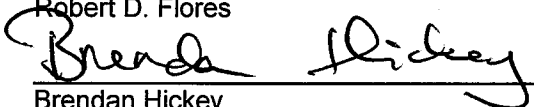
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